



PRESS RELEASE

August 31, 2022

**IMAPS to host Workshop on
Strategies to Revitalize the On-Shore Packaging and Assembly Defense Industrial Base**

The International Microelectronics Assembly and Packaging Society (IMAPS) will host a one-day Workshop to discuss and promote strategies to improve on-shore packaging and assembly capabilities on October 3, 2022, at the Hynes Convention Center, Boston, Massachusetts. This workshop will be followed by the IMAPS 2022 Symposium, October 3-6 at the same location. The mission of the workshop is to engage the workforce community to identify solutions, which address US Government and Defense requirements, critical to the onshoring of the microelectronic assembly and packaging supply chain.

The workshop will draw together industry engineers, researchers, leaders, and other stakeholders involved in microelectronics packaging and assembly and those working in the US Government and Defense Industrial Base environments. The program was put together with the intent is to educate, strategize and have collaborative discussions. Workshop attendees are invited to join the IMAPS 2022 Symposium welcome reception that evening.

The Technical Program will feature:

- A SHIP session kicking off with keynote speaker Daniel J. Drum (Naval Surface Warfare Center, Crane Division) presenting the DoD's State-of-the-Art (SOTA) Heterogeneous Integrated Packaging (SHIP) Program.
- Breakout sessions focused on Substrates & Materials Manufacturing, Enabling & Disruptive Technologies, Reliability, and Heterogeneous Integration.
- Two panel sessions on the Defense Industrial Base (DIB) Ecosystem, and Workforce Development.

For full program information and registration, visit www.imaps.org/onshoring

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